CST8V06S Dual N-Ch 60V Fast Switching MOSFETs

★ Green Device Available
★ Super Low Gate Charge
★ Excellent CdV/dt effect decline
★ Advanced high cell density Trench technology

CST8V06S Product Summary

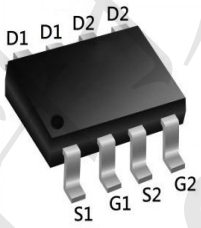
BVDSS	RDSON	ID
60V	25mΩ	8.0A

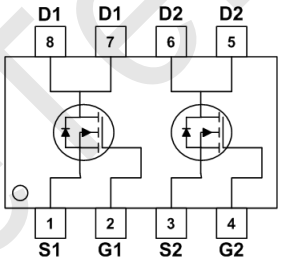
CST8V06S Description

The CST8V06S is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The CST8V06S meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

CST8V06S SOP8 Pin Configuration





CST8V06S Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	8.0	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ 10V[1]	5.5	A
I_{DM}	Pulsed Drain Current[2]	25	A
EAS	Single Pulse Avalanche Energy[3]	28	mJ
I_{AS}	Avalanche Current	10	A
P_D@T_A=25℃	Total Power Dissipation[4]	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

CST8V06S Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient [1]	---	80	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	25	℃/W

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CST8V06S Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	60	-	-	V
Gate-Body Leakage Current		I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T_J=25°C	I_{DSS}	V_{DS} = 60V, V_{GS} = 0V	-	-	1	μA
	T_J=100°C			-	-	100	
Gate-Threshold Voltage		$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1.2	1.7	2.5	V
Drain-Source on-Resistance[4]		$R_{DS(on)}$	V_{GS} = 10V, I_D = 10A	-	25	32	mΩ
			V_{GS} = 4.5V, I_D = 5A	-	31	40	
Forward Transconductance[4]		g_{fs}	V_{DS} = 5V, I_D = 10A	-	15.5	-	S
Dynamic Characteristics[5]							
Input Capacitance		C_{iss}	V_{DS} = 30V, V_{GS} =0V, f =1MHz	-	1355	-	pF
Output Capacitance		C_{oss}		-	60	-	
Reverse Transfer Capacitance		C_{rss}		-	49	-	
Gate Resistance		R_G	f =1MHz	-	1.2	-	Ω
Switching Characteristics[5]							
Total Gate Charge		Q_g	V_{GS} = 10V, V_{DD} = 30V, I_D= 10A	-	22	-	nC
Gate-Source Charge		Q_{gs}		-	4.2	-	
Gate-Drain Charge		Q_{gd}		-	6.9	-	
Turn-on Delay Time		$t_{d(on)}$	V_{GS} =10V, V_{DD} = 30V, R_G = 3Ω, I_D= 10A	-	6.4	-	ns
Rise Time		t_r		-	15.3	-	
Turn-off Delay Time		$t_{d(off)}$		-	25	-	
Fall Time		t_f		-	7.6	-	
Body Diode Reverse Recovery Time		t_{rr}	I_F=10A, dI_F/dt=100A/μs	-	26	-	ns
Body Diode Reverse Recovery Charge		Q_{rr}		-	45	-	nC
Drain-Source Body Diode Characteristics							
Diode Forward Voltage[4]		V_{SD}	I_S = 10A, V_{GS} = 0V	-	-	1.2	V
Continuous Source Current	T_C=25°C	I_S	-	-	-	8	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C
2. The EAS data shows Max. rating . The test condition is V_{DD}=25V, V_{GS}=10V, L=0.4mH, I_{AS}=14A
3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

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CST8V06S Typical Performance Characteristics

Figure1: Output Characteristics

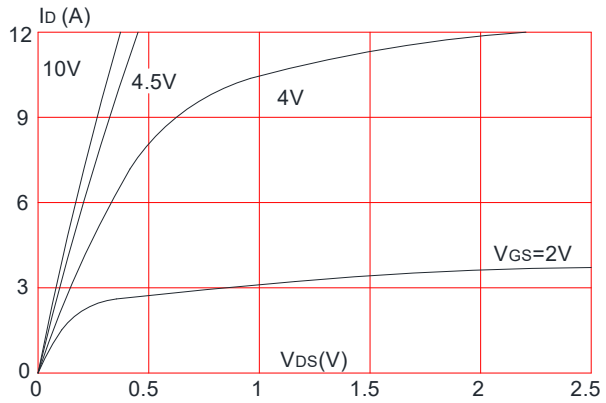

Figure 2: Typical Transfer Characteristics

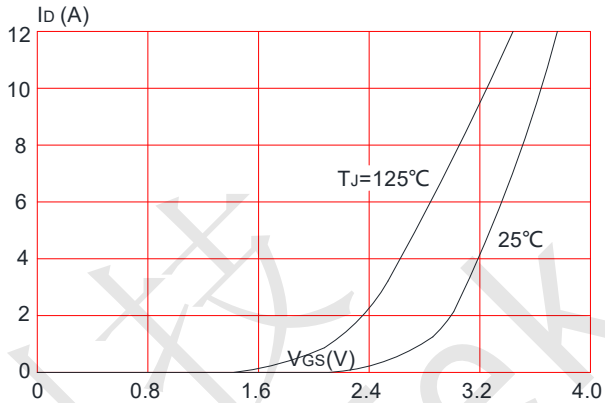

Figure 3: On-resistance vs. Drain Current

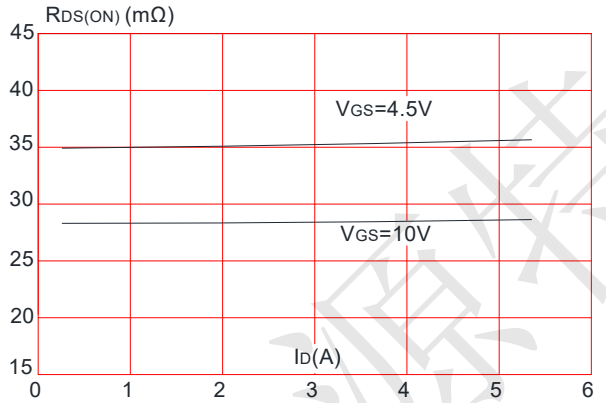

Figure 4: Body Diode Characteristics

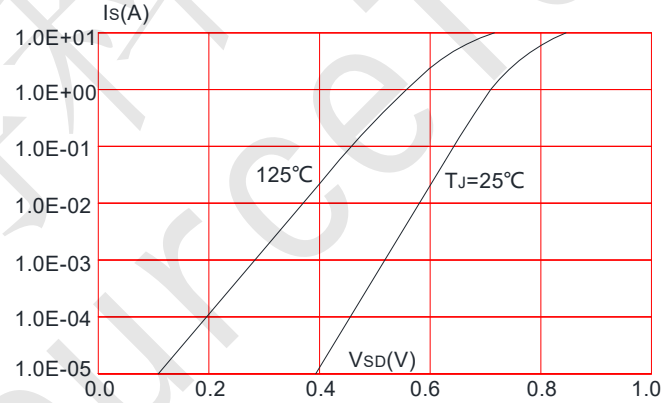

Figure 5: Gate Charge Characteristics

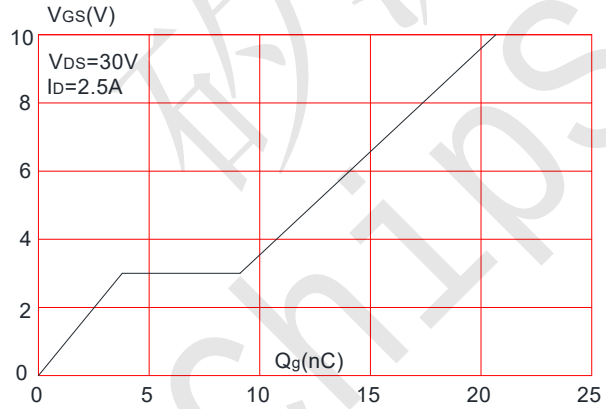

Figure 6: Capacitance Characteristics

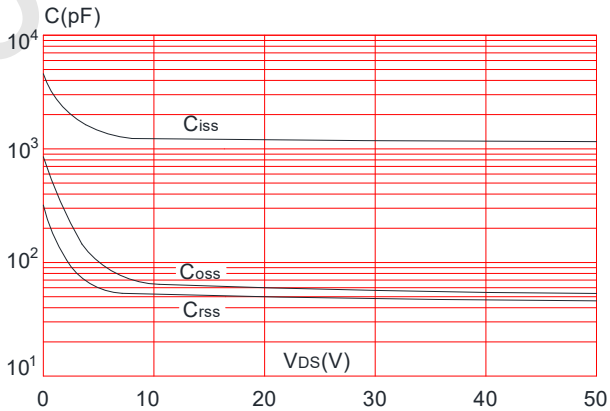

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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

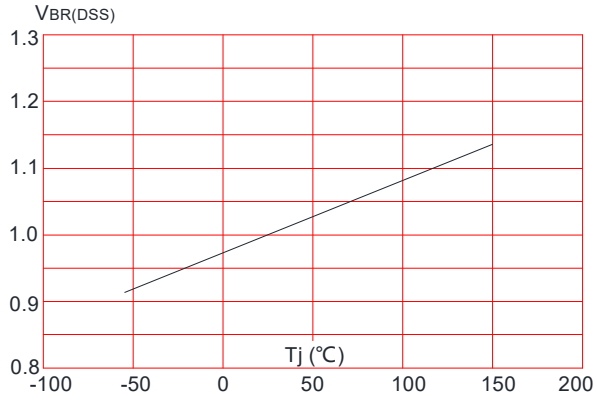


Figure 8: Normalized on Resistance vs. Junction Temperature

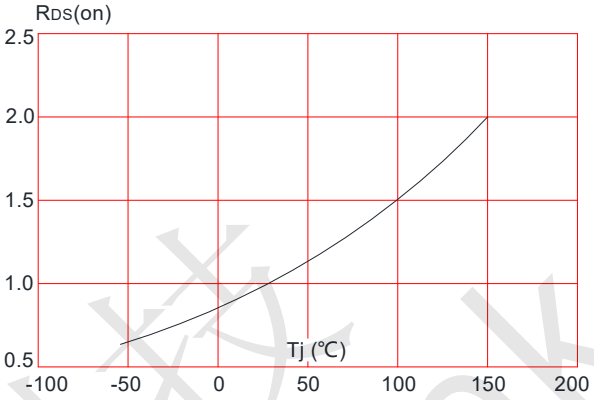


Figure 9: Maximum Safe Operating Area

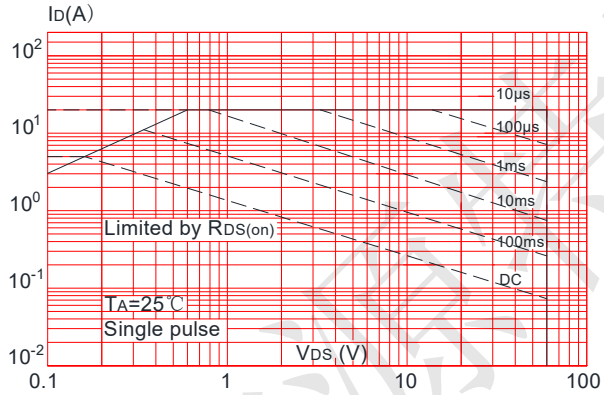


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

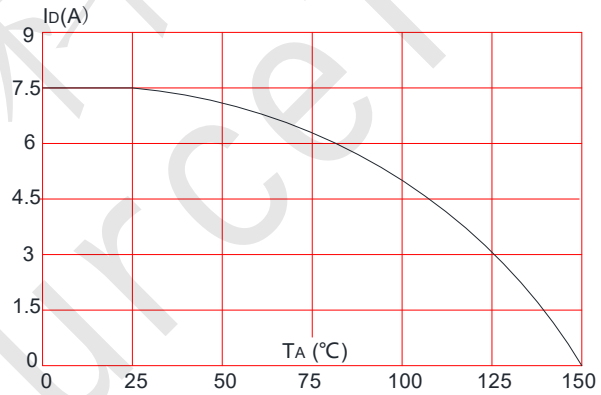
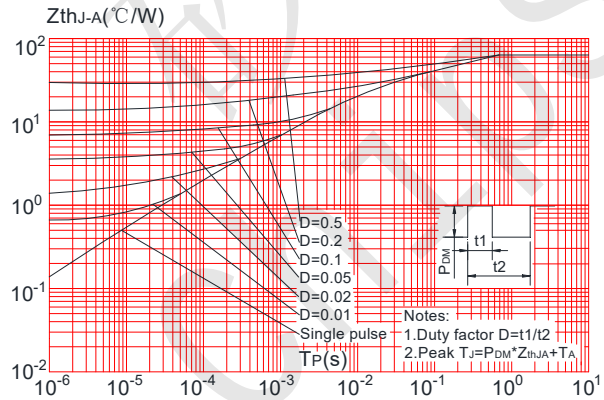


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



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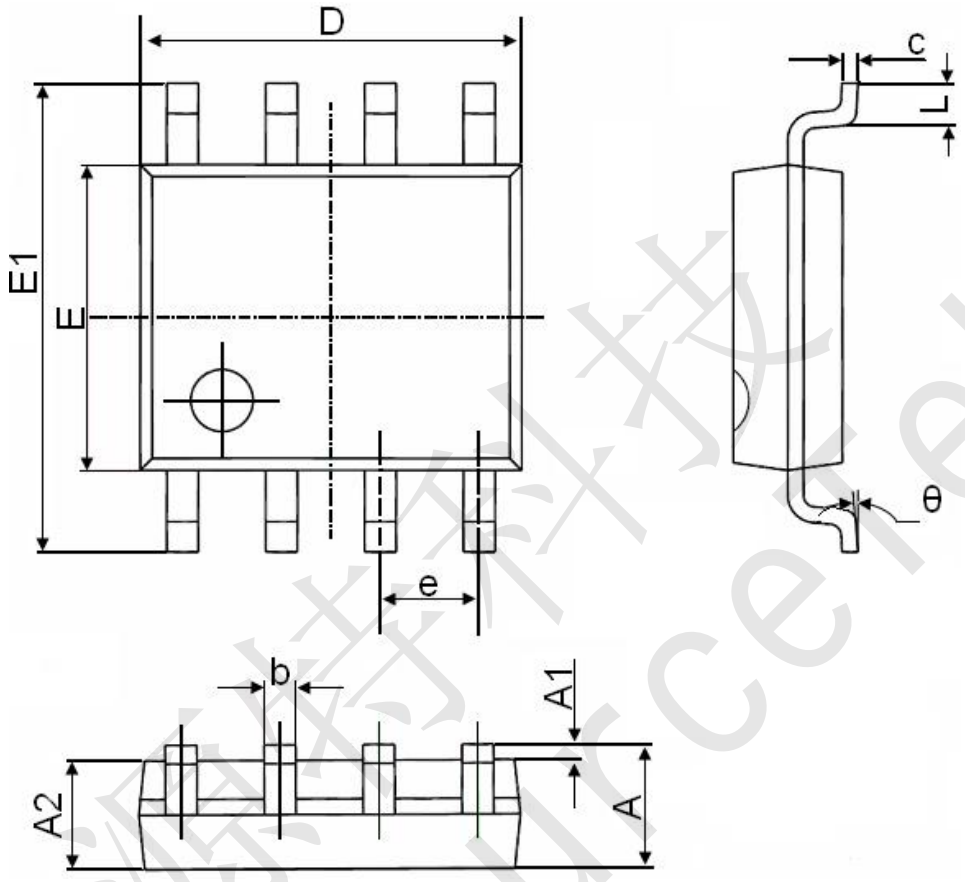
CST8V06S SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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